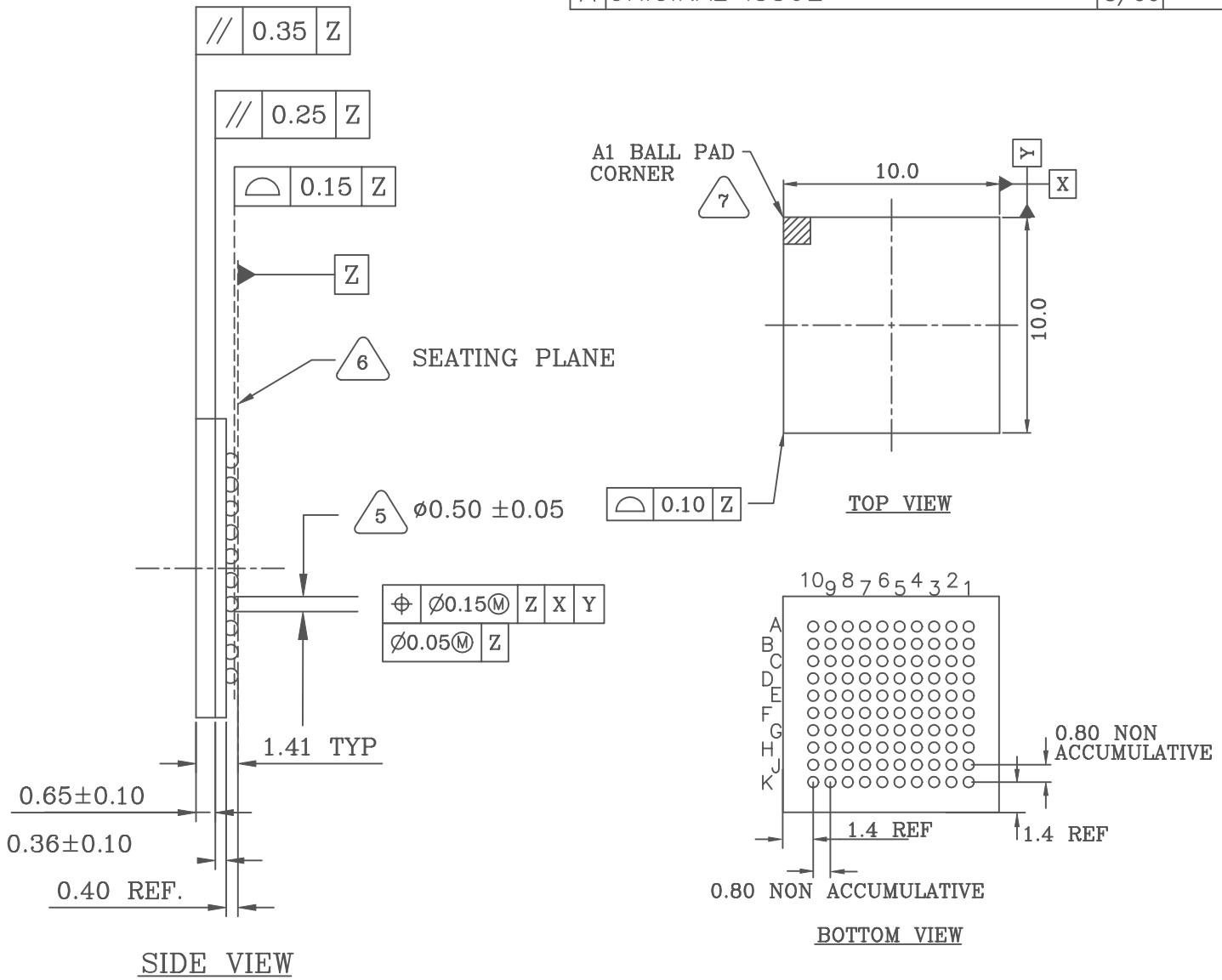


REVISIONS			
LTR.	DESCRIPTION	DATE	APPROVED
A	ORIGINAL ISSUE	8/00	



NOTES:

- ⑦. A1 BALL PAD CORNER I.D. IS IDENTIFIED BY LASER MARKED DOT AT THE CORNER.
- ⑥. PRIMARY DATUM Z AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- ⑤. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM Z.
- 4. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
- 3. SOLDER BALL POSITION DESIGNATION PER JESD 95-1, SPP-010.
- 2. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994.
- 1. ALL DIMENSIONS ARE IN MILLIMETERS

SIGNATURE		DATE					
DOC. CONTROL:							
ENGR. MGR:				TITLE			
MFG. ENGR:				MARKETING OUTLINE 100L CHIP SCALE BGA (10X10) 0.8MM PITCH, 1.41 THICK, 2 LAYER			
CHECKED BY:	TWM	8/00	SIZE	FSCM NO.	PART NO.	56-G6008-001	REV.
DRAWN BY:	JDH	8/00	A				A
DO NOT SCALE DRAWING				SCALE	N/A	SHEET	1 of 1